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## **(54) OPTOELECTRONICS DEVICE AND MANUFACTURING METHOD THEREFOR**

(57)Abstract:

PURPOSE: To economically manufacture optoelectronic devices by providing and fixing a lens-coupling optical element, so that the light generated in a larger chip hits almost vertically to the optoelectronic device.

CONSTITUTION: A laser chip 1 is, while a side surface adjoining a resonator surface of the laser chip 1 is provided with a mirror film 5, an a common supporter 2, between two supporting members 3 and 4 inclined by 45° is provided with respect to the resonator surface. Then, the light generated in the laser chip 1 is directed upwards, almost vertical to the upper surface of the common supporter 5, and at least on one supporting member 5, a lens-coupling optical element 6 is provided and fixed, so that the light in the laser chip 1 hits the lens-coupling optical element 6 almost vertically. Thus, optoelectronic devices are manufactured economically.

